



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20080416000B

**Qualification of Jiangyin Changdian Advanced Packaging Co., LTD (JCAP) as a
Qualified Source for Assembly Test Processing of TI - SLL NanoStar Products
(Packages YZP / YZT / YZV)
Final Change Notification / Sample Request**

Date: 5/29/2014
To: MOUSER PCN

Dear Customer:

The purpose of revision B is to add 1 device from this change notification which was not included on the Original PCN. The affected device is highlighted in yellow in the Product Affected section of this document.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659


20080416000B
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74AUP2G125YZPR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20080416000B		PCN Date:	05/29/2014	
Title:	Qualification of Jiangyin Changdian Advanced Packaging Co., LTD (JCAP) as a Qualified Source for Assembly Test Processing of TI - SLL NanoStar Products (Packages YZP / YZT / YZV)				
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037		Dept: Quality Services
Proposed 1st Ship Date:	08/29/2014		Estimated Sample Availability:	Date provided at sample request	
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
PCN Details					
Description of Change:					
<p>The purpose of revision B is to add 1 device highlighted in yellow in the Product Affected Section. The proposed first ship date applies only to the yellow highlighted device: SN74AUP2G125YZPR.</p> <p>Texas Instruments Standard Linear and Logic (SLL) is pleased to announce the successful qualification of Jiangyin Changdian Advanced Packaging Co., LTD (JCAP) in China, as a qualified Assembly/Test site for YZV, YZT, and YZP wafer chip scale packages for SLL NanoStar devices/packages listed in this PCN, (current device list by package noted below for reference). Jiangyin Changdian Advanced Packaging Co., LTD (JCAP) will provide a full turnkey solution for wafer chip scale packages for SLL. NanoStar is a trademark for Texas Instruments' wafer chip scale package.</p> <p>* Samples of the device SN74AUP2G125YZPR is available upon request.</p> <p>Additional samples available and can be built upon request.</p>					
Reason for Change:					
The successful qualification of Jiangyin Changdian Advanced Packaging Co., LTD (JCAP) as an Assembly/Test site will further improve Texas Instruments' support of current and future production needs for the SLL NanoStar product.					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
We do not anticipate a negative impact on fit, form, function nor reliability.					
Changes to product identification resulting from this PCN:					
Assembly Site					
ASEK		Assembly Site Origin (22L)		ASO: ASF	
JCAP-AT		Assembly Site Origin (22L)		ASO: JCP	
Sample product shipping label to show code location only - not actual product label					
					
Assembly Site Code: ASEK = 7 , JCAP-AT =P					

Product Affected:			
CA9536YZPR	SN74AUP1G07YZPR	SN74LVC1G14YZPR	SN74LVC2G17YZPR
SN74AUC1G00YZPR	SN74AUP1G08YZPR	SN74LVC1G14YZVR	SN74LVC2G240YZPR
SN74AUC1G02YZPR	SN74AUP1G125YZPR	SN74LVC1G175YZPR	SN74LVC2G241YZPR
SN74AUC1G04YZPR	SN74AUP1G125YZTR	SN74LVC1G17YZPR	SN74LVC2G32YZPR
SN74AUC1G06YZPR	SN74AUP1G126YZPR	SN74LVC1G17YZTR	SN74LVC2G34YZPR
SN74AUC1G07YZPR	SN74AUP1G17YZPR	SN74LVC1G17YZVR	SN74LVC2G34YZTR
SN74AUC1G08YZPR	SN74AUP1G240YZPR	SN74LVC1G18YZPR	SN74LVC2G38YZPR
SN74AUC1G08YZPRL	SN74AUP1G32YZPR	SN74LVC1G19YZPR	SN74LVC2G53YZPR
SN74AUC1G08YZTR	SN74AUP1G34YZPR	SN74LVC1G240YZPR	SN74LVC2G66YZPR
SN74AUC1G125YZPR	SN74AUP1G57YZPR	SN74LVC1G27YZPR	SN74LVC2G66YZTR
SN74AUC1G125YZTR	SN74AUP1G58YZPR	SN74LVC1G29SYZPR	SN74LVC2G74YZPR
SN74AUC1G126YZPR	SN74AUP1G58YZTR	SN74LVC1G29YZPR	SN74LVC2G79YZPR
SN74AUC1G126YZTR	SN74AUP1G74YZPR	SN74LVC1G3157YZPR	SN74LVC2G80YZPR
SN74AUC1G14YZPR	SN74AUP1G79YZPR	SN74LVC1G3208YZPR	SN74LVC2G86YZPR
SN74AUC1G17YZPR	SN74AUP1G80YZPR	SN74LVC1G32YZPR	SN74LVC2GU04YZPR
SN74AUC1G17YZPRL	SN74AUP1G97YZPR	SN74LVC1G32YZTR	SN74LVC2T45YZPR
SN74AUC1G19YZPR	SN74AUP1G98YZPR	SN74LVC1G332YZPR	SN74LVC3G04YZPR
SN74AUC1G240YZPR	SN74AUP1G99YZPR	SN74LVC1G34YZPR	SN74LVC3G06YZPR
SN74AUC1G32YZPR	SN74AUP1T57YZPR	SN74LVC1G34YZTR	SN74LVC3G07YZPR
SN74AUC1G66YZPR	SN74AUP1T97YZPR	SN74LVC1G34YZVR	SN74LVC3G14YZPR
SN74AUC1G74YZPR	SN74AUP1T98YZPR	SN74LVC1G373YZPR	SN74LVC3G17YZPR
SN74AUC1G74YZTR	SN74AUP2G08YZPR	SN74LVC1G373YZTR	SN74LVC3G34YZPR
SN74AUC1G79YZPR	SN74AUP2G125YZPR	SN74LVC1G374YZPR	SN74LVC3GU04YZPR
SN74AUC1G80YZPR	SN74AUP2G126YZPR	SN74LVC1G386YZPR	TPS22921YZTR
SN74AUC1G86YZPR	SN74AVC1T45YZPR	SN74LVC1G38YZPR	TS3A24159YZPR
SN74AUC1GU04YZPR	SN74AVC2T45YZPR	SN74LVC1G57YZPR	TS3DS26227YZTR
SN74AUC2G00YZPR	SN74AVC2T45YZTR	SN74LVC1G58YZPR	TS5A1066YZPR
SN74AUC2G02YZPR	SN74AVCH1T45YZPR	SN74LVC1G66YZPR	TS5A2066YZPR
SN74AUC2G04YZPR	SN74AVCH2T45YZPR	SN74LVC1G79YZPR	TS5A22364YZPR
SN74AUC2G04YZTR	SN74LVC1404YZPR	SN74LVC1G80YZPR	TS5A23166YZPR
SN74AUC2G06YZPR	SN74LVC1G00YZPR	SN74LVC1G86YZPR	TS5A23166YZTR
SN74AUC2G07YZPR	SN74LVC1G02YZPR	SN74LVC1G97YZPR	TS5A23167YZPR
SN74AUC2G08YZPR	SN74LVC1G02YZTR	SN74LVC1G98YZPR	TS5A26542YZTR
SN74AUC2G08YZTR	SN74LVC1G04YZPR	SN74LVC1G99YZPR	TS5A3153YZPR
SN74AUC2G125YZPR	SN74LVC1G04YZTR	SN74LVC1GU04YZPR	TS5A3154YZPR
SN74AUC2G126YZPR	SN74LVC1G04YZVR	SN74LVC1GU04YZTR	TS5A3157YZPR
SN74AUC2G240YZPR	SN74LVC1G06YZPR	SN74LVC1GU04YZVR	TS5A3159AYZPR
SN74AUC2G241YZPR	SN74LVC1G06YZVR	SN74LVC1T45YZPR	TS5A3159AYZTR
SN74AUC2G32YZPR	SN74LVC1G07YZPR	SN74LVC2G00YZPR	TS5A3166YZPR
SN74AUC2G32YZTR	SN74LVC1G07YZTR	SN74LVC2G02YZPR	TS5A3167YZPR
SN74AUC2G34YZPR	SN74LVC1G07YZVR	SN74LVC2G04YZPR	TS5A3359YZPR
SN74AUC2G34YZTR	SN74LVC1G0832YZPR	SN74LVC2G06YZPR	TS5A6542YZPR
SN74AUC2G53YZPR	SN74LVC1G08YZPR	SN74LVC2G07YZPR	TS5A6542YZTR
SN74AUC2G53YZTR	SN74LVC1G10YZPR	SN74LVC2G08YZPR	TXB0101YZPR
SN74AUC2G66YZPR	SN74LVC1G11YZPR	SN74LVC2G08YZTR	TXB0102YZPR
SN74AUC2G79YZPR	SN74LVC1G123YZPR	SN74LVC2G125YZPR	TXB0104YZTR
SN74AUC2G80YZPR	SN74LVC1G125YZPR	SN74LVC2G126YZPR	TXS0101YZPR
SN74AUC2G86YZPR	SN74LVC1G126YZPR	SN74LVC2G132YZPR	TXS0102YZPR
SN74AUC2GU04YZPR	SN74LVC1G132YZPR	SN74LVC2G14YZPR	TXS0102YZTR
SN74AUP1G00YZPR	SN74LVC1G139YZPR	SN74LVC2G157YZPR	TXS0104EYZTR

Qualification Data:

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1: TS3DS26227YZT (MSL1-260C)

Package Construction Details

Assembly & Bump Site:	JCAP	Bump Composition:	SnAgCu
# Pins-Designator, Family:	12-YZT, WCSP/DSBGA	Bump Diameter:	0.25mm

Qualification: ☐ Plan ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot 1	Lot 2	Lot 3
**Steady-state Life Test	150C (300 Hrs)	116/0	116/0	116/0
**High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Unbiased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Temperature Cycle	-55C/+125C (1000 Cyc)	77/0	77/0	77/0
Manufacturability (Assembly)	(per mfg site specifications)	Pass	Pass	Pass
Moisture Sensitivity	MSL1-260C	12/0	12/0	12/0

** Moisture Preconditioning (MSL1-260C)

Qual Vehicle 2: TS5A26542YZTR (MSL1-260C)

Package Construction Details

Assembly & Bump Site:	JCAP	Bump Composition:	SnAgCu
# Pins-Designator, Family:	12-YZT, WCSP/DSBGA	Bump Diameter:	0.25mm

Qualification: ☐ Plan ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot 1	Lot 2	Lot 3
Manufacturability (Assembly)	(per mfg site specifications)	Pass	Pass	Pass

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com